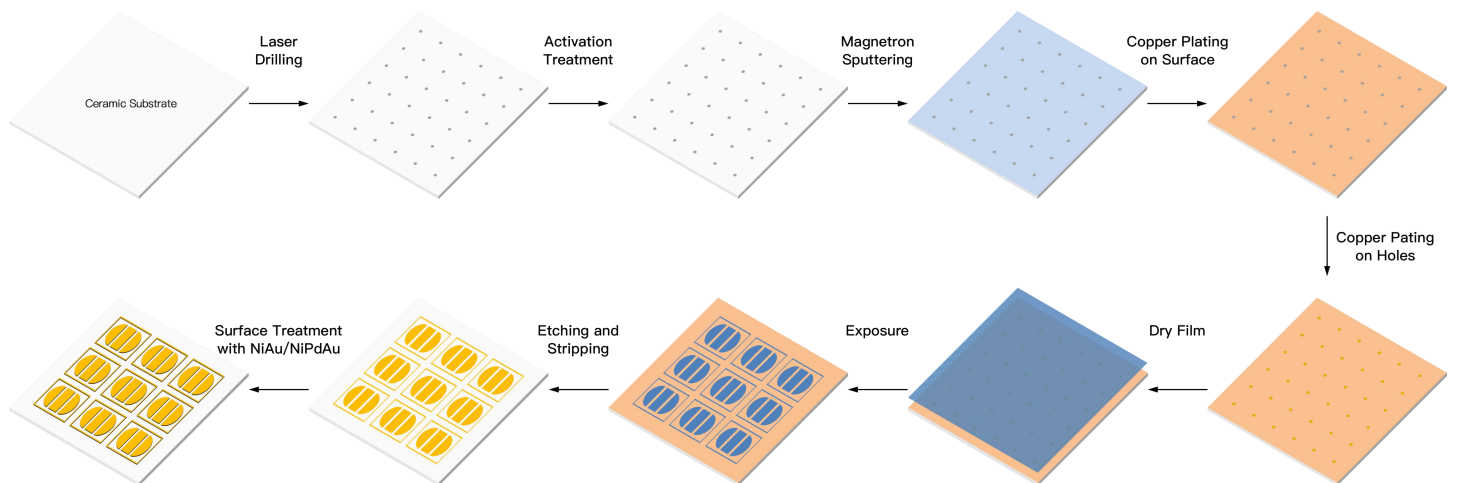


DPC – Direct Plated Copper

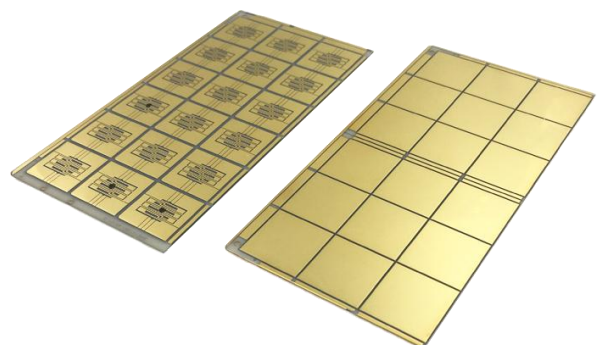
■ Introduction

DPC is a newest development in the field of Ceramic Substrate PCBs, by magnetron sputtering technology to deposit a metal layer (Ti/Cu target) on the surface of the ceramic substrate which result in copper thickness' ranging from 10um to 130um, and then photolithography to form circuit patterns, electroplating is used to fill in the gaps and thicken the metal circuit layer, and the solderability and oxidation resistance of the substrate is improved through surface treatment, finally remove the dry film, and etch the seed layer to complete the substrate.



■ Features

1. High thermal stability and excellent electrical conductivity
2. Excellent mechanical stability, good adhesion
3. High operating temperatures
4. Excellent electrical insulation
5. Good heat spreading



■ Applications

Cells for Solar Concentrators



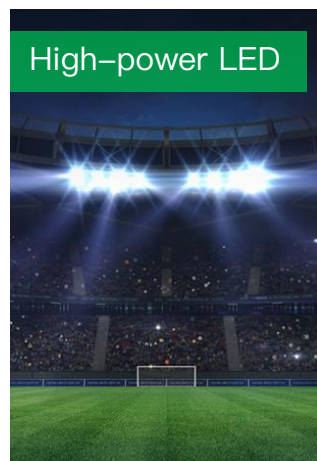
Hybrid and Electric Automobile Power Management Electronics



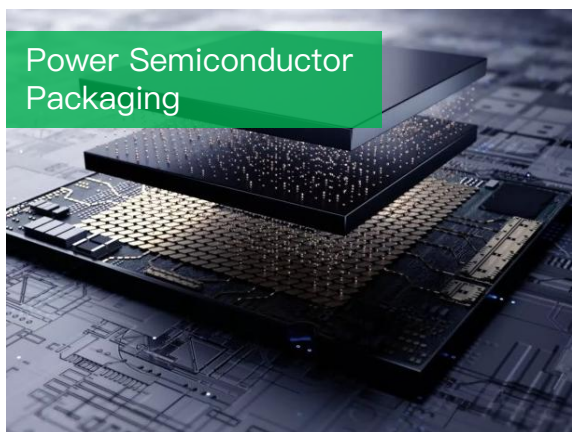
Sensor in Automotive Motor Control



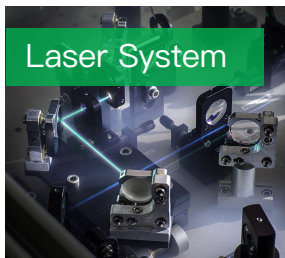
High-power LED



Power Semiconductor Packaging



Laser System



Semiconductor Modules Such as IGBT



Packages for RF



Microwave Devices



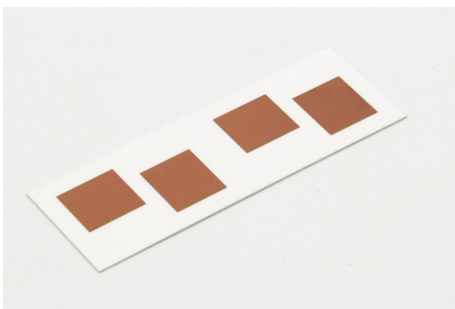
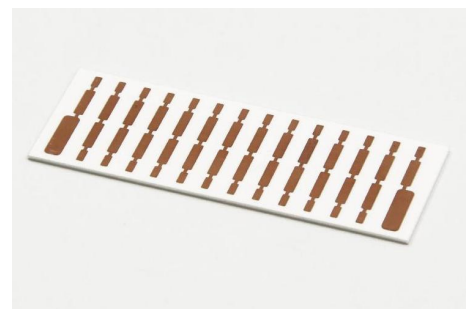
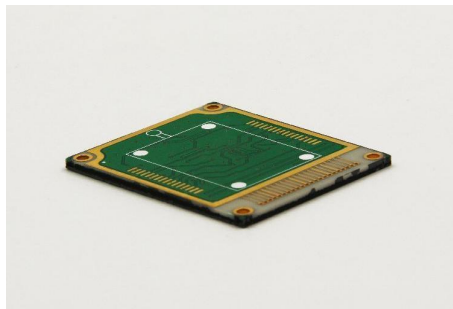
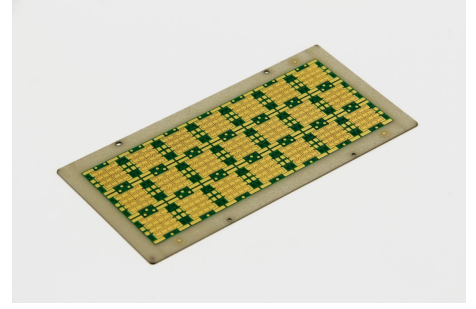
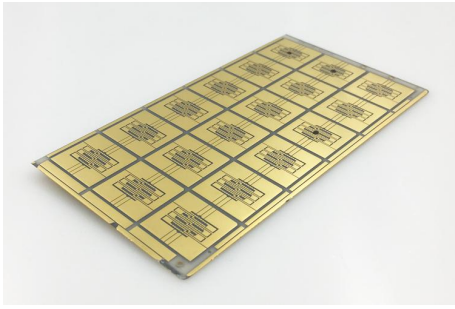
■ Ceramic Materials Properties

Item	Unit	Alumina	AlN
Content	%	96% Alumina	–
Density	g/cm ³	≥3.7	≥3.3
Thermal conductivity	W/m·K	> 24	>170
Coefficient of thermal expansion	10 ⁻⁶ /K	6.5~7.5 (20°C~300°C)	4.6 (20°C~300°C)
Flexural strength	MPa	>350	>350
Dielectric loss	x10 ⁻⁴ [1MHz]	3	3.8
Dielectric constant	1MHz	9.8	9
Dielectric strength	Kv/mm	14.5	17
Volume Resistivity	Ω·cm	>10 ¹⁴	>10 ¹⁴
Young's Modulus of Elasticity	GPa	340	320

■ Capability

Item	Description	Capability
Material	–	Al ₂ O ₃ , AlN
Ceramic Thickness	–	0.38–1.0mm
Copper Thickness (When Distance Between Copper)	<0.2mm	10–50μm
	0.2–0.5mm	30–80μm
	0.6–1.0mm	30–150μm
	<0.075mm	30–60μm
Copper Width (When Copper Thickness)	<35μm	≥0.075mm
	35–100μm	≥0.1mm
	≥100μm	≥0.15mm
Ag Thickness	–	≥0.4μm
Surface Treatment	NiAu/NiPdAu	Ni: 5±2.5μm Pd: >0.05μm Au: >0.05μm

■ Show Case





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